## MA2SD24

### Silicon epitaxial planar type

For super high speed switching

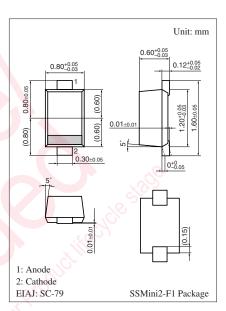
#### ■ Features

- Forward current (Average)  $I_{F(AV)} = 200$  mA rectification is possible
- Small reverse current I<sub>R</sub>

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	20	V
Repetitive peak reverse voltage	V <sub>RRM</sub>	20	V
Peak forward current	$I_{FM}$	300	mA
Forward current (Average)	I <sub>F(AV)</sub>	200	mA
Non-repetitive peak forward surge current *	I <sub>FSM</sub>	1	A
Junction temperature	Tj	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C

Note) \*: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

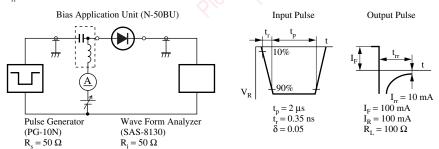


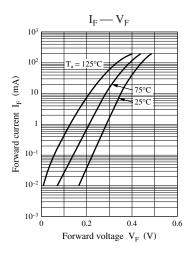
Marking Symbol: 5L

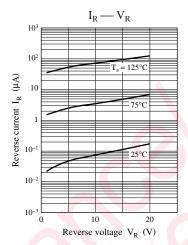
#### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

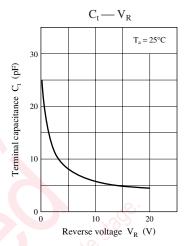
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F</sub>	$I_F = 200 \text{ mA}$		0.50	0.58	V
Reverse current	$I_R$	$V_R = 10 \text{ V}$		0.1	1.0	μΑ
Terminal capacitance	$C_{t}$	$V_R = 0 V, f = 1 MHz$	190	25		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$		3		ns
		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. Absolute frequency of input and output is 250 MHz.
  - 4. \*: t<sub>rr</sub> measurement circuit









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